

# MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



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GDT



PLED

Product data sheet

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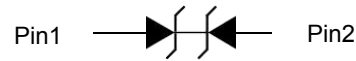
## Features

- Ultra low leakage: nA level
- Low clamping voltage
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity test
    - Air discharge:  $\pm 25\text{kV}$
    - Contact discharge:  $\pm 25\text{kV}$
  - IEC61000-4-4 (EFT) 40A (5/50ns)
- RoHS Compliant
- AEC-Q101 qualified



## Applications

- USB 2.0 power and data line
- Set-top box and digital TV
- Digital video interface (DVI)
- Notebook Computers
- SIM Ports
- 10/100 Ethernet
- LIN BUS



Circuit Diagram

SOD-323

## Mechanical Characteristics

- Package: SOD-323
- Lead Finish: Lead Free
- UL Flammability Classification Rating 94V-0
- Quantity Per Reel: 3000pcs
- Reel Size: 7 inch

## Absolute Maximum Ratings (T<sub>amb</sub>=25°C unless otherwise specified)

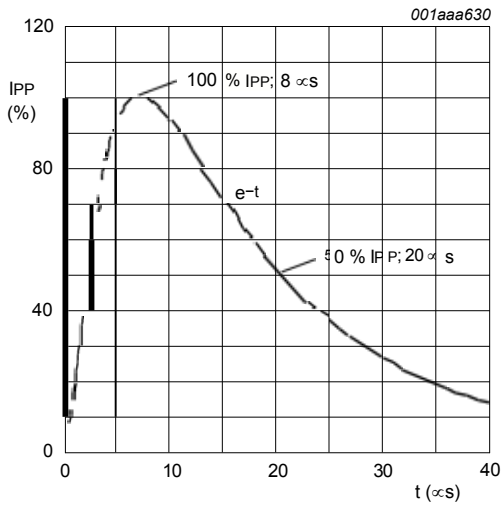
Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20 $\mu$ s)	P <sub>pp</sub>	180	W
ESD per IEC 61000-4-2 (Air)	V <sub>ESD</sub>	$\pm 20$	Kv
ESD per IEC 61000-4-2 (Contact)		$\pm 20$	
Operating Temperature Range	T <sub>J</sub>	-55 to +125	°C
Storage Temperature Range	T <sub>STJ</sub>	-55 to +150	°C

**Electrical Characteristics** (TA=25°C unless otherwise specified)

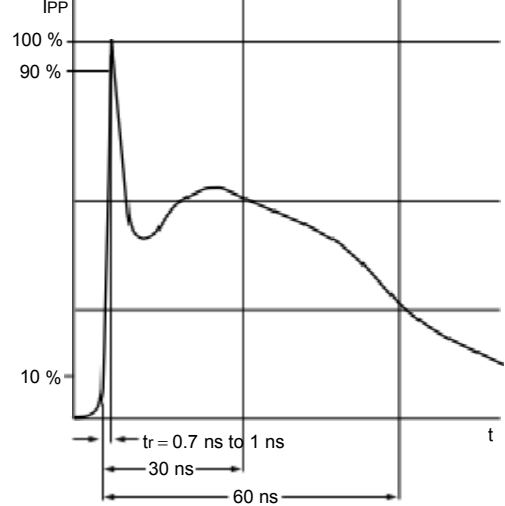
P/N	V <sub>RWM</sub> (V)	V <sub>BR</sub> (V)	I <sub>T</sub> (mA)	V <sub>C</sub> @1A	V <sub>C</sub>		I <sub>R</sub> μA (Max)	C (Pf) (Typ.)
					(Max)	(@A)		
PESD1LIN-MS	15	18.9	5	25	44	5	0.05	13
	24	27.8	5	40	70	3	0.05	13

**Characteristic Curves**

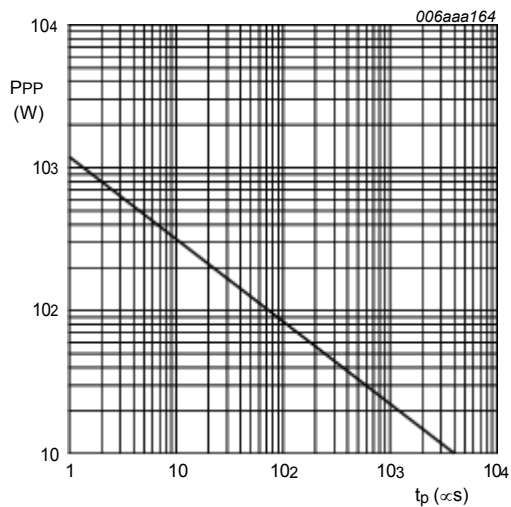
**Fig 1. 8/20 μs pulse waveform according to IEC 61000-4-5**



**Fig 2. ESD pulse waveform according to IEC 61000-4-2**

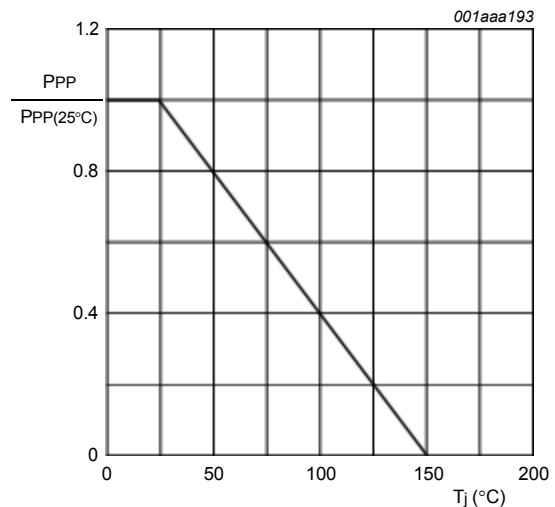


**Fig 3. Peak pulse power as a function of exponential pulse duration; typical values**

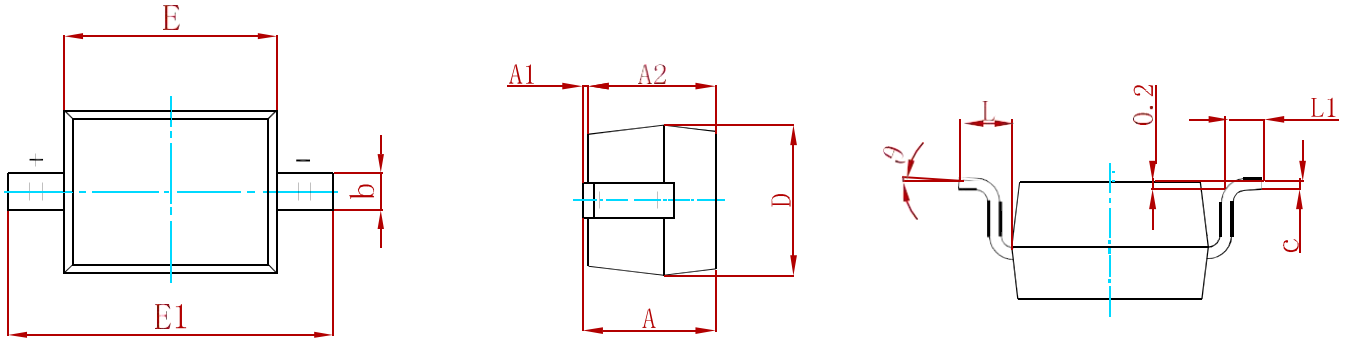


T<sub>amb</sub> = 25 °C

**Fig 4. Relative variation of peak pulse power as a function of junction temperature; typical values**

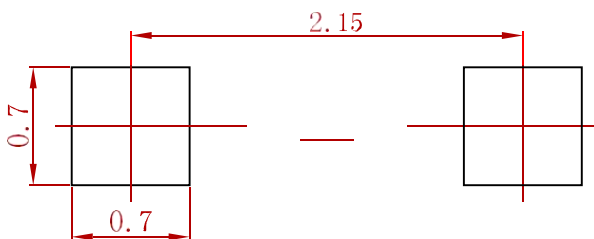


**PACKAGE MECHANICAL DATA**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

**Suggested Pad Layout**



**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05mm.
3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

P/N	PKG	QTY
PESD1LIN-MS	SOD-323	3000

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